L Number	Hits	Search Text	DB	Time stamp
-	308	(Dispersion solution slurry) and ('cmp' near5 polishing) and	USPAT;	2004/09/27 14:26
		(silica\$2alumina silicon\$2aluminum near2 oxide silicon near2	US-PGPUB	
1		aluminum near2 oxide)		
í <b>-</b>	124	(Dispersion solution slurry) and polishing and	USPAT;	2004/09/27 14:22
		(silica\$2alumina silicon\$2aluminum near2 oxide)	US-PGPUB	
-	50	(Dispersion solution slurry) and ('cmp' polishing) and	EPO; JPO;	2004/09/27 16:50
		(silica\$2alumina silicon\$2aluminum near2 oxide silicon near2	DERWENT;	
k		aluminum near2 oxide)	IBM TDB	
-	4	("5891205" "5382272" "5858813" "5954997").did.	USPAT;	2004/09/27 14:22
			US-PGPUB	